Gp/1765

IN THE UNITED **ES** PATENT AND TRADEMARK OFFICE SJO990204US1 Docket No: Applicant: Hsiao et al. Serial No: 09/754,235 Group Art Unit: 1765 Examiner: Ahmed, Shamim Filing Date: January 3, 200 LISHING THICKNESS CONTROL IN MAGNETIC CHEMICAL MECHA **HEAD FABRICATION** Box Non Fee Amendment Commissioner for Patents Washington, D.C. 20231 AMENDMENT TRANSMITTAL \mathbf{X} Transmitted herewith is an amendment for this application. **STATUS** \boxtimes Applicant is a small entity -- verified statement: attached. already filed. other than a small entity. X**EXTENSION OF TIME** Applicant petitions for an extension of time under 37 CFR 1.136 for the total number of months checked below: Fee for other than Fee for Extension small entity small entity (months) \$ 110.00 \$ 55.00 one month \$ 410.00 \$205.00 two months three months \$ 930.00 \$465.00 four months \$1,450.00 \$725.00 Fee \$ If an additional extension of time is required please consider this a petition therefor. months has already been secured and the fee paid An extension for is deducted from the total fee due for the total months therefor of \$ of extension now requested. Extension fee due with this request \$

CERTIFICATE OF MAILING (37 CFR 1.8(a))

I hereby certify that this paper (along with any referred to as being attached or enclosed) is being deposited on January 8, 2003 with the U.S. Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, Washington, D.C., 20231.

Date: January 8, 2003

Patricia Beilmann

X

Applicant believes that no extension of time is required. However, this conditional petition is hereby made to provide for the possibility that applicant has inadvertently overlooked the need for a petition for extension of time.

FEE FOR CLAIMS

The fee for claims (37 CFR 1.16(b)-(d)) has been calculated as shown below:

	(Col. 1)	(Col. 2)	(Col. 3)	SMALL ENTITY		OR	OTHER THAN A SMALL ENTITY	
	Claims Remaining After Amendment	Highest No. Previously Paid For	Present Extra	Rate	Addit. Fee		Rate	Addit. Fee
Total	Minus *0*	=		x9=	\$		x18=	\$
Indep.	Minus *0*	=		x42=	\$	·	x84=	\$
	T PRESENTATION OF MULT	IPLE DEP. CLAIN	И	+140=	\$		x280=	\$
				TOTAL ADDIT. FEE	\$	OR	TOTAL ADDIT. FEE	\$

\square	No additional fee for claims required. Total additional fee for claims required \$				
	FEE PAYMENT				
	Attached is a check in the sum of \$ Charge Account No. 08-3240 the sum of \$ A duplicate of this transmittal is attached.				
	FEE DEFICIENCY				
X	In the event that: a) no check to cover the filing fee is enclosed, b) any above-referenced check is inadvertently omitted or lost, or c) any enclosed check is in an amount less than or greater than the required fee, the Commissioner is authorized to charge any required fees, additional fees, or credit any overpayment to Deposit Account 08-3240. A duplicate of this authorization is enclosed for that purpose.				
\boxtimes	Attached is a postcard for date-stamped return as confirmation of receipt of these materials.				
Date:	January 8, 2003 ROBERT O. GUILLOT				

Reg. No. 28,852

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<u>IN THE UNITED STATES PATENT & TRADEMARK OFFICE</u>

#6/A Ma 1/4/03

Applicant:

Hsiao et al.

Atty Docket: SJO990204US1

Serial No.:

09/754,235

Art Unit: 1765

Filing Date:

January 3, 2001

Examiner: Ahmed, Shamim

Title: CHEMICAL MECHANICAL POLISHING THICKNESS CONTROL IN

MAGNETIC HEAD FABRICATION

Box Non Fee Amendment Commissioner for Patents Washington, D.C. 20231

FIRST AMENDMENT

Sir:

1

Responsive to the Office Action mailed October 8, 2002, please amend the aboveidentified application as follows:

In the Claims

Please delete claims 4, 16 and 28 without prejudice.

Please amend the claims by replacing the pending like numbered claims with the clean claims set forth below. A marked up version of these claims is provided in Attachment A.

- 1. (Once amended) A method for controlling the end point of the chemical mechanical
- 2 polishing (CMP) of a surface having a plurality of projecting components fabricated thereon,
- 3 comprising the steps of:
 - fabricating a plurality of upwardly projecting components upon a substrate surface;
 - fabricating a first material layer that is deposited in part upon a top surface of said
- 6 projecting components and in part upon a top surface of said substrate;
- 7 fabricating a CMP polishing end stop layer above said first material layer;
- 8 fabricating a polishable layer above said stop layer;